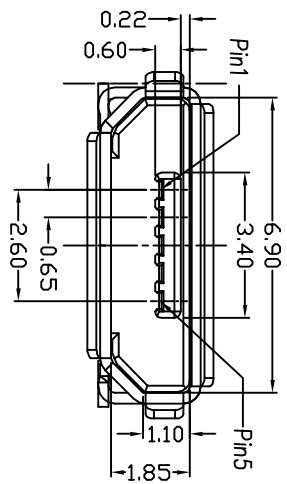
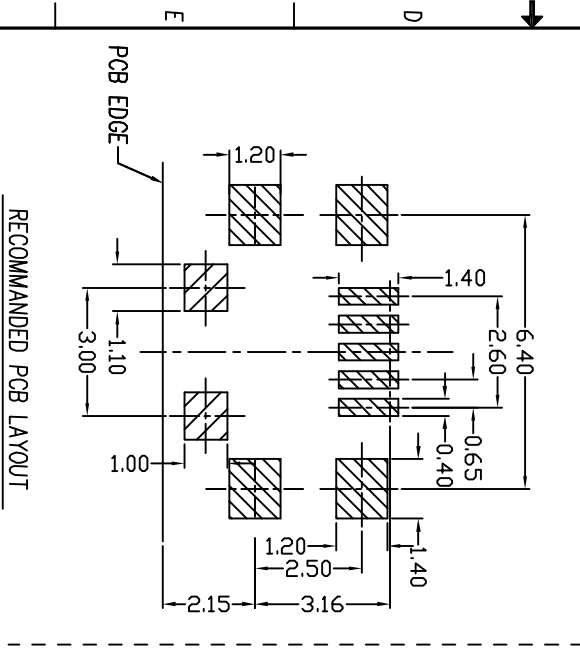
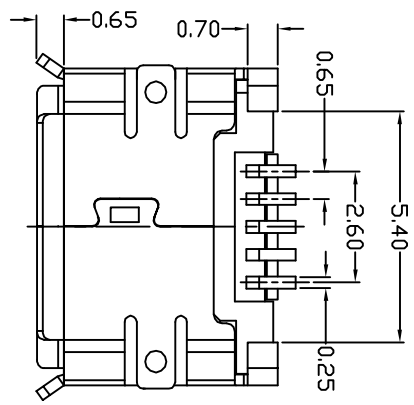
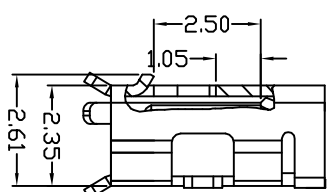
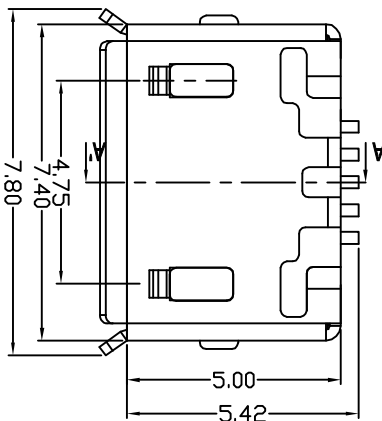
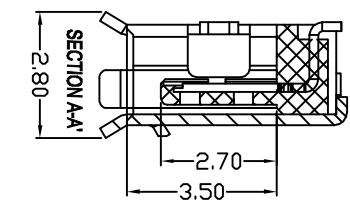
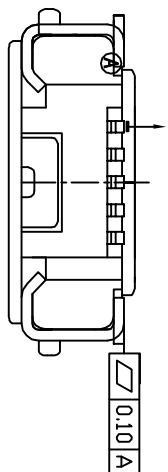


| REV. | EQN NO | LOCATIONS | DESCRIPTION | DATE | REVISER | APPD |
|------|--------|-----------|-------------|------|---------|------|
| | | | | | | |



- Notes:
- Materials:
 - 1.1 Housing: High temperature thermoplastic with g.f: UL94 v-0.
 - 1.2 Contact: copper alloy, t=0.20mm, NI 50U", Gold 1U".
 - 1.3 Shell: copper alloy, t=0.25mm, NI 80U", SN 80U".
 - Specifications:
 - 2.1. Current rating: 1 A Max.
 - 2.2. Dielectric withstanding: voltage: 100 V(ac) for 1 min.
 - 2.3. Contact resistance: 50 mW Max.
 - 2.4. Insulation resistance: 100 MW Min.
 - 2.5. Total mating force: 3.57 Kgf Max.
 - 2.6. Total unmating force: 1.0 Kgf Min. 0.81~2.05 Kgf Min. after 10000 insertion/extraction cycles
 - 2.7. Temperature range: -30°C~+80°C

| | | | |
|-------------------------|----------|--------------------------------|--------------|
| PART NO: 1-MD05SMXXX-01 | | MATERIAL: SEE NOTE | |
| MODEL NO: | | FINSH: SEE NOTE | |
| UNIT: mm | SIZE: A4 | COLOR: SEE NOTE | TITLE: |
| TOLERANCE UNSPECIFIED | | Micro usb SS B Type (四脚全贴) 有孔型 | |
| .x | ±0.38 | DR: ?/?/? | DWG NO: A107 |
| .xx | ±0.25 | CHK: | REV: A |
| .xxx | ±0.13 | APP: | SCALE: 1:1 |
| ANG. | ±2° | | SHEET: 1/1 |

| No. | Nome | Q'ty | Finish |
|-----|---------|------|--------|
| 3 | Shell | 1 | N/A |
| 2 | Contact | 5 | N/A |
| 1 | Housing | 1 | N/A |